

IMAPS-UK/IEEE-EPS Online Conference

“Thermal Management”

Wednesday 25th and Thursday 26th November 2020

[Register Here](#)



Thermal Management Conference Highlights:

Keynote Presentations on:
Automotive/Industrial Needs

Thermal Interface Materials

Electro-thermal Cooling

Embedded Cooling

Additive Manufacturing

Modelling and Metrology

Challenges and Solutions for Keeping Electronics Cool

IMAPS-UK and the UK and Ireland Chapter of IEEE Electronics Packaging Society (EPS) will hold an Online Conference over two afternoons on Wednesday 25 and Thursday 26 November 2020 on the topic of Thermal Management, where you can learn about the latest developments in passive and active cooling, materials, measurement and modelling to address the challenges of enhancing thermal dissipation from advanced electronics systems.

This Online Conference will cover all aspects of designing, manufacturing and testing of high thermal performance electronics, where miniaturisation, costs and reliability are critical features that need to be optimised.

5 Key Reasons to attend:

End User Needs – challenges in transportation and industrial sectors

Passive Cooling – overcoming thermal management issues through advanced materials and processes

Active Cooling – thermoelectric generators, additive manufacturing, embedded cooling

Measurement and Testing – ensuring reliability/fitness for purpose

Simulation – shortening the design and validation cycle

Book your place now at the IMAPS-UK “Thermal Management” Online Conference. IMAPS and IEEE EPS Members can register for **FREE**.

Registration Prices:

	<i>Delegates</i>
<i>IMAPS and IEEE-EPS Member</i>	<i>FREE</i>
<i>IMAPS Student Member</i>	<i>FREE</i>
<i>Non Member</i>	<i>£50</i>
<i>Prices - £ exclude VAT</i>	
“Where Industry Meets Online”	



Provisional Thermal Management Online Conference Agenda (subject to change):

Wednesday 25th November 2020

Passive Thermal Management and Materials/Metrology

13:30 Welcome and Introduction to IMAPS-UK

13:45 Keynote: Challenges for Thermal Management in the Automotive Industry – David Bock, BMW

14:15 Packaging Challenges – to be confirmed

14:45 Thermal Interface Materials – Graham Wilson, Indium Corporation

15:15 – 15:30 Break

15:30 Metrology – Jiyu Wu, NPL

16:00 Thermomechanical Design/Modelling – Chris Bailey, University of Greenwich

16:30 Open Discussion – Where are the Gaps? What needs to be done?

Thursday 26th November 2020

Active Thermal Management and Design/Modelling/Simulation

13:00 Recap of Day 1

13:15 Keynote: Thermal Management in Industrial Motors – Imran Agha, Siemens

13:45 Electro-thermal Cooling – to be confirmed

14:15 Additive Manufacturing for Cooling Structures – Stephen Mellor, Hieta

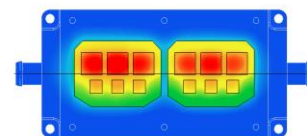
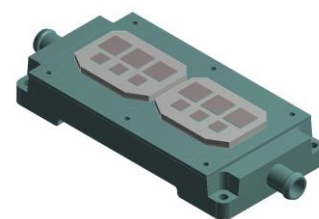
14:45 – 15:00 Break

15:00 Embedded Cooling and Jet Impingement – Song Lin, Columbia Staver

15:30 Design, Modelling and Simulation – Robin Bornoff, Mentor Graphics

16:00 Open Discussion – Where are the Gaps? What needs to be done?

16:30 Closing Remarks & End



IMAPS-UK Conferences and Workshops:

IMAPS-UK Conferences and Workshops offer delegates the opportunity to learn about the issues and complexities of microelectronics assembly technologies. They provide professional development through in-depth, real-life insights into materials, processes and equipment applied to current and future electronics.

About IMAPS-UK:

The International Microelectronics, Assembly and Packaging Society (IMAPS) is the largest society dedicated to the advancement and growth of microelectronics and advanced electronics packaging. IMAPS-UK is a registered Charity and plays a leading role in the UK's advanced electronics industry.

The Society's objectives are achieved through regional seminars, workshops, major international conferences and exhibitions, the publication of newsletters and technical papers as well as other activities relevant to promoting knowledge within the industry.

IEEE Electronics Packaging Society (EPS)

The IEEE Electronics Packaging Society is the leading international forum for scientists and engineers engaged in the research, design and development of revolutionary advances in microsystems packaging and manufacturing.



JOIN TODAY AND START SEEING THE BENEFITS!

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